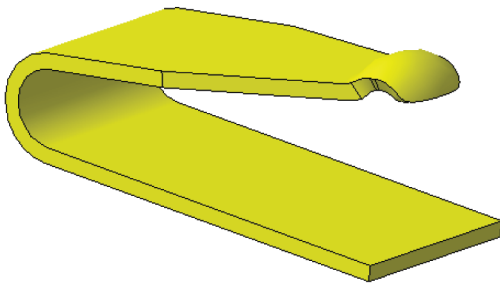


# C-Clip Connector

Pulse Part Number W9909



Ideal for board-to-antenna applications  
Spring contact for positive connection  
Surface mount technology; solder reflowable

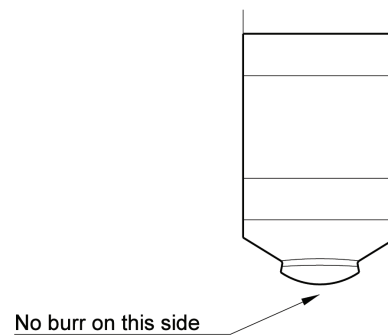
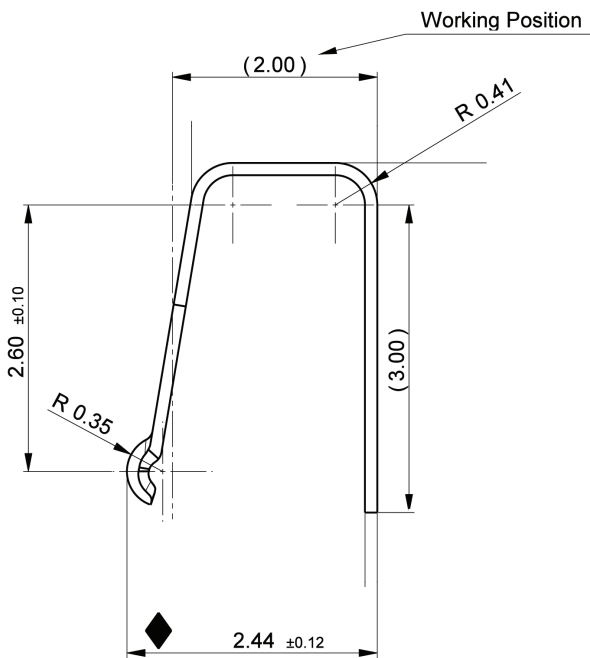


### Features

- PWB Footprint 3.2 x 1.7 mm
- Tape & Reel Packaging
- RoHS Compliant Product

### Applications

- Antenna Contacts
- W3530 Antenna RF Contacts

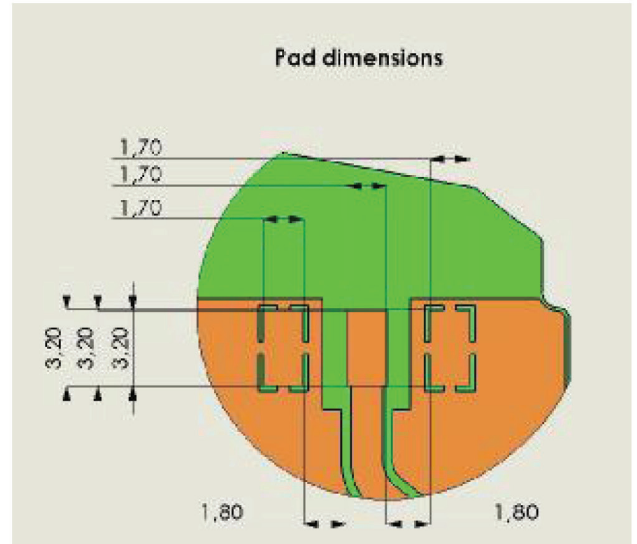
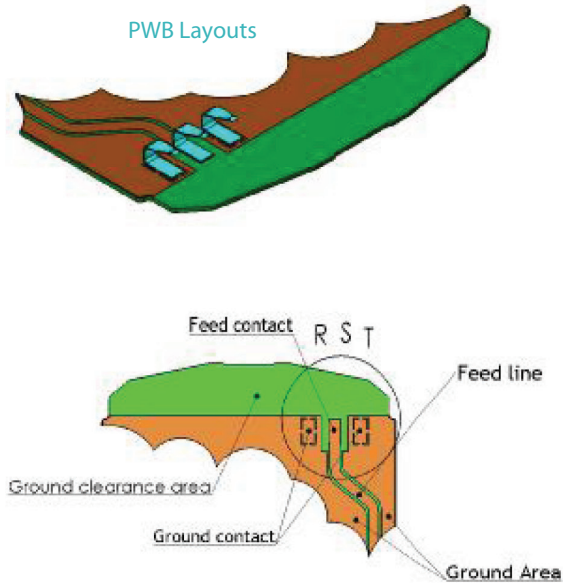


# C-Clip Connector

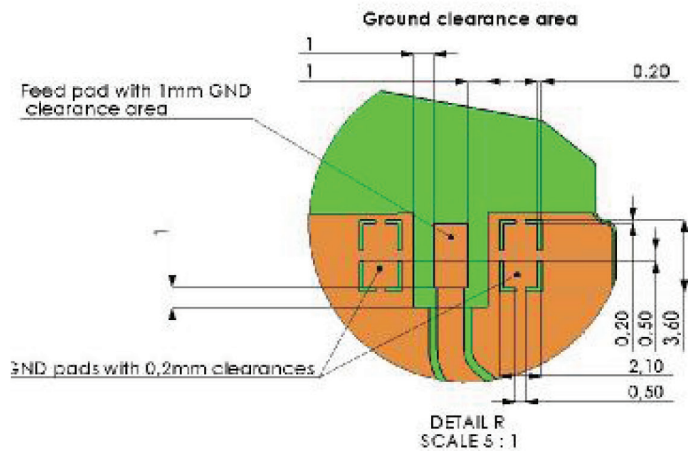
Pulse Part Number W9909

## W9909 C-Clip Configuration and Dimensions

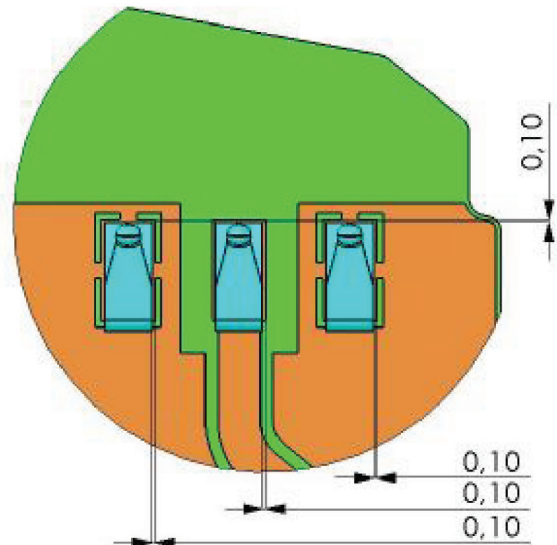
PWB Pad Dimensions and C-Clip Position for W9909



Ground Clearance Area for W9909 C-Clip



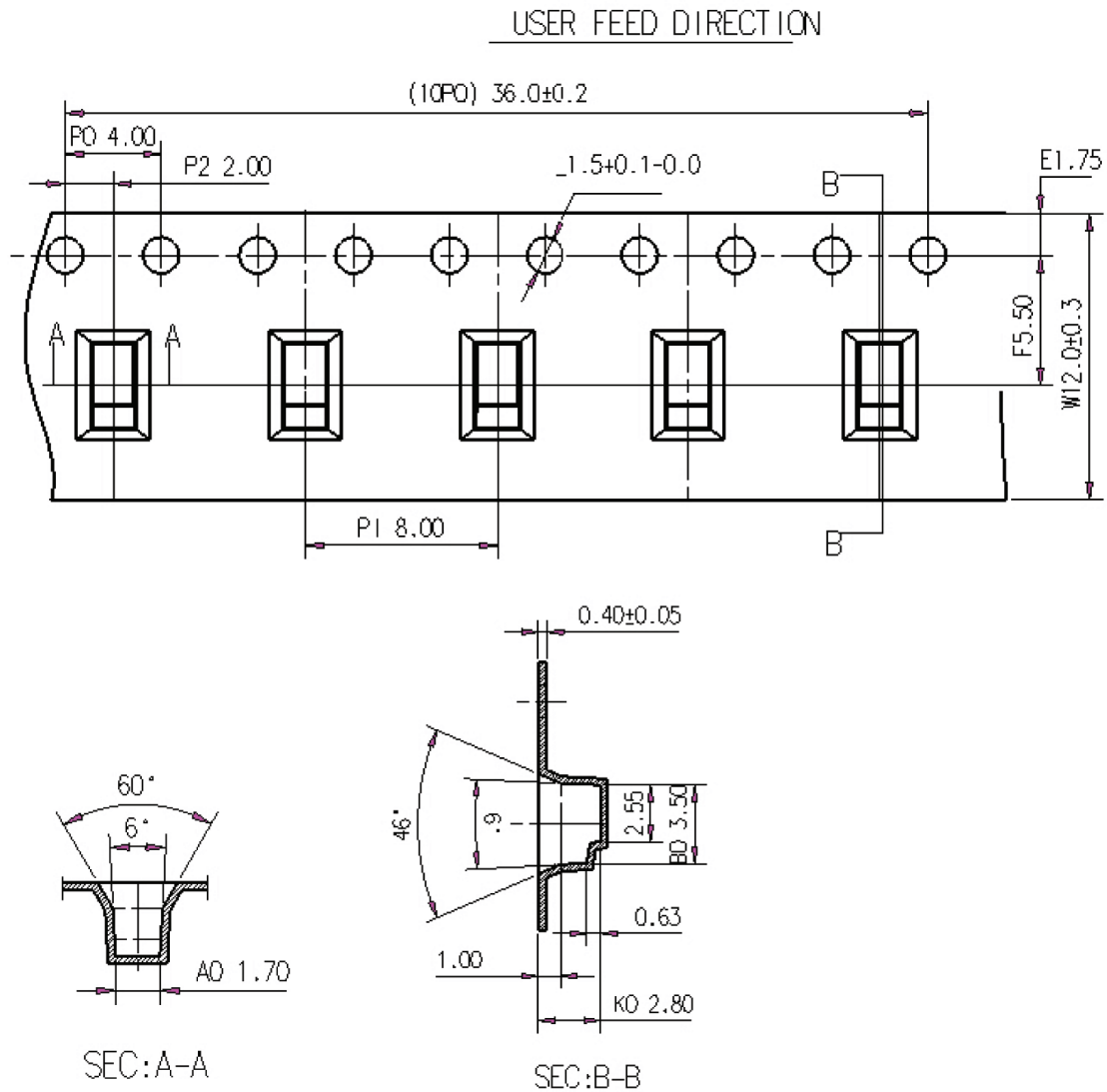
C-clip position on PWB layout



# C-Clip Connector

Pulse Part Number W9909

Reel packing is used for the C-clip.



**NOTE:**

1. MATERIAL:PS Clear-Thickness:0.40±0.05mm
2. Packing Length Per 22" Reel: 60 Meters
3. Component Load Per 13" Reel: 5000 Pcs
4. 10 SPROCKET HOLE CUMULATIVE TOLERANCE: ±0.2
5. CARRIER CAMBER IS WITHIN 1mm IN 100mm

**Figure 2. Connector packing.**

# C-Clip Connector

Pulse Part Number W9909

## W9909 Connector Soldering

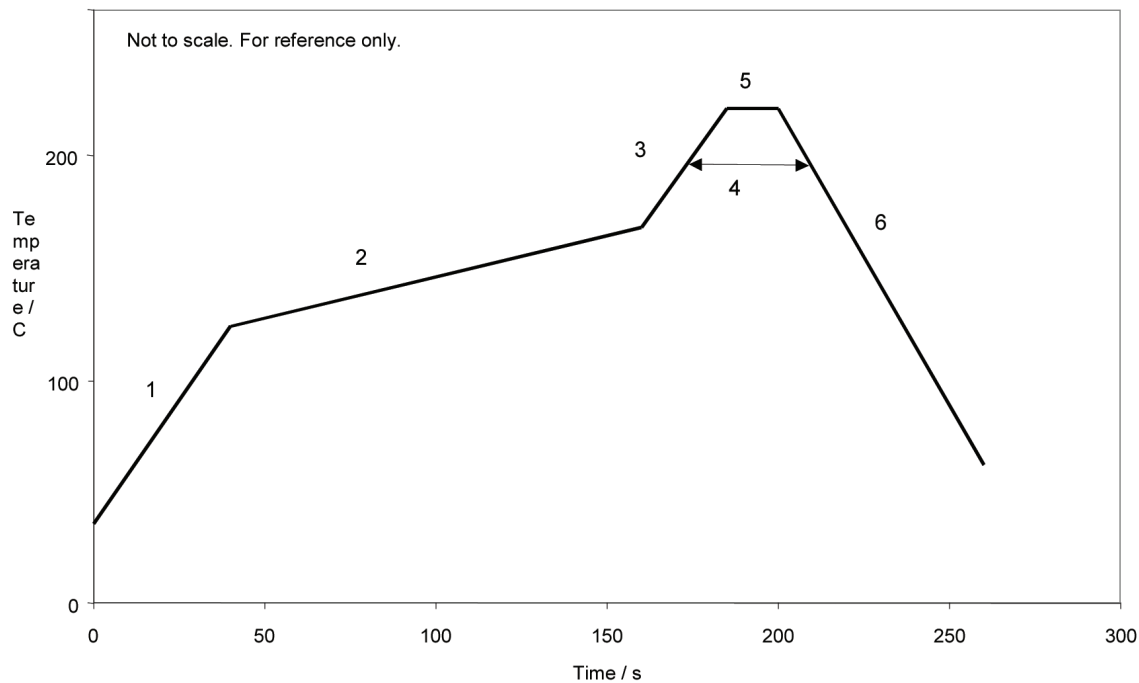
### Recommendation for reflow soldering process

Printing stencil thickness 0.15 to 0.25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C.

The temperature profile recommendations for reflow solder process are presented in Figure 1 and 2. The reflow profile presented in Figure 2 describes maximum reflow temperatures.

Figure 1 - Minimum temperature profile recommendation for reflow soldering process

	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5°C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3°C/s
4	Time above 217°C	Max 30 sec
5	Peak temperature in reflow	230°C for 10 seconds
6	Temperature gradient in cooling	Max -5°C/s

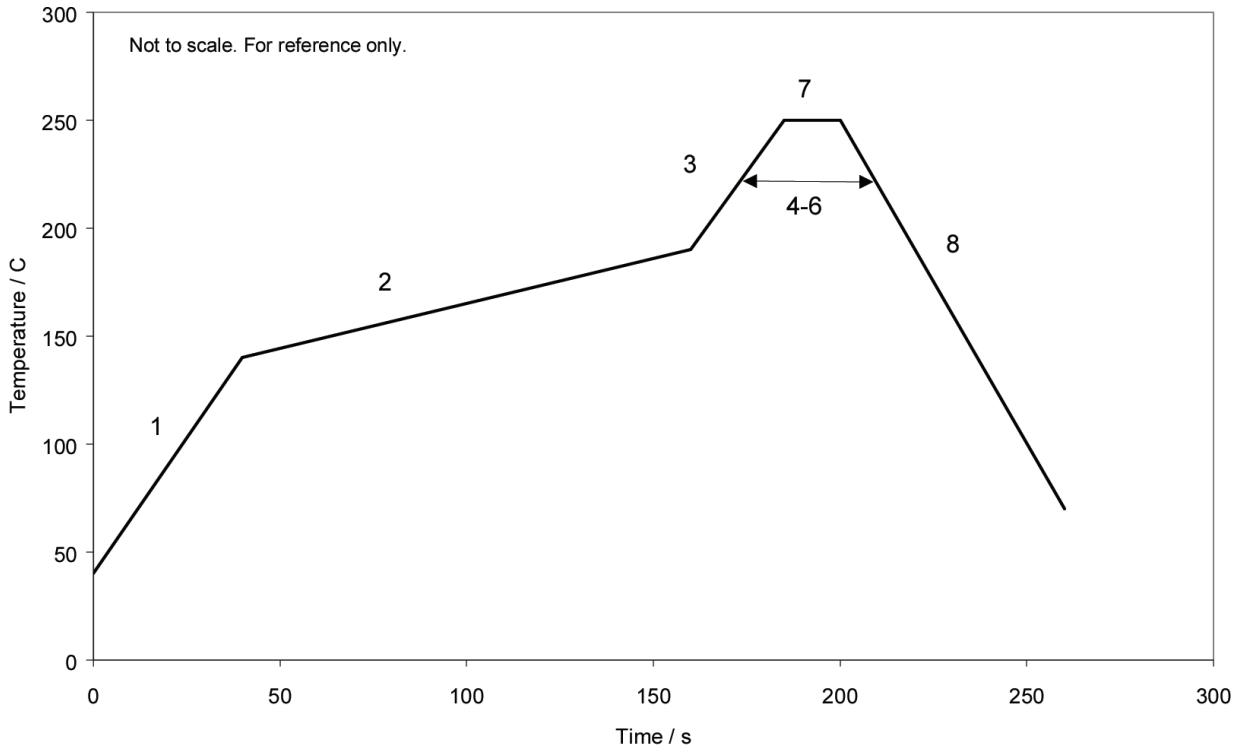


# C-Clip Connector

Pulse Part Number W9909

Figure 2 - Maximum temperature profile recommendation for reflow soldering process

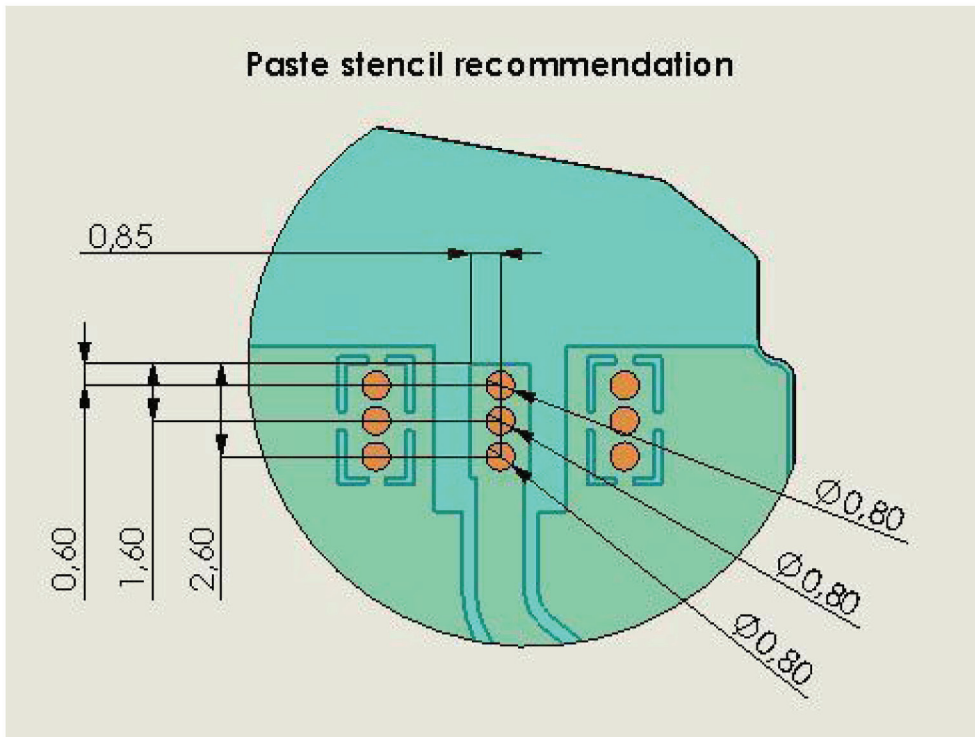
	Method of heat transfer	Controlled hot air convection
1	Average temperature gradient in preheating	2.5°C/s
2	Soak time	2-3 minutes
3	Max temperature gradient in reflow	3°C/s
4	Time above 217°C	Max 60 sec
5	Time above 230°C	Max 50 sec
6	Time above 250°C	Max 10 sec
7	Peak temperature in reflow	260°C for 5 seconds
8	Temperature gradient in cooling	Max -5°C/s



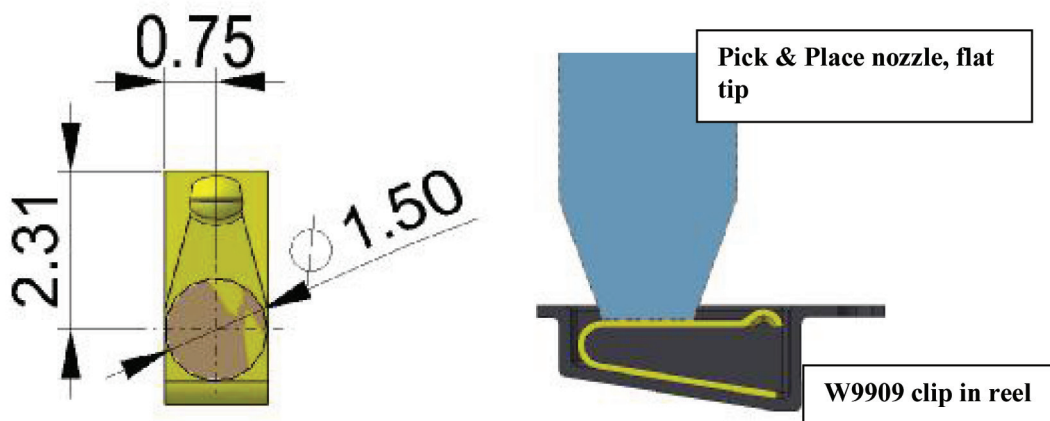
# C-Clip Connector

Pulse Part Number W9909

## SMT notes



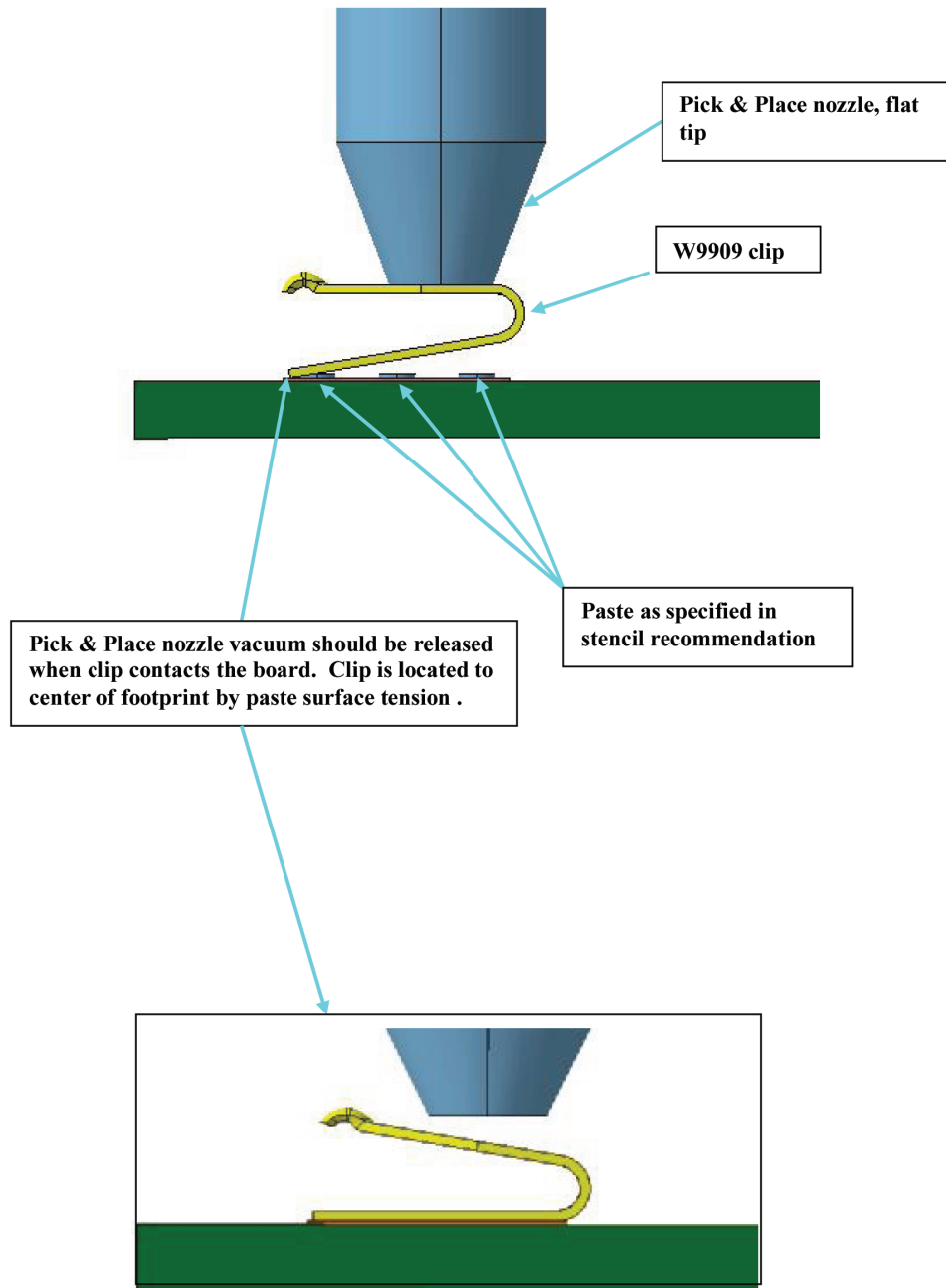
## Pick & Place area



# C-Clip Connector

Pulse Part Number W9909

## SMT setup recommendation



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